

Status of CMS Phase-II Upgrade

Dayong Wang

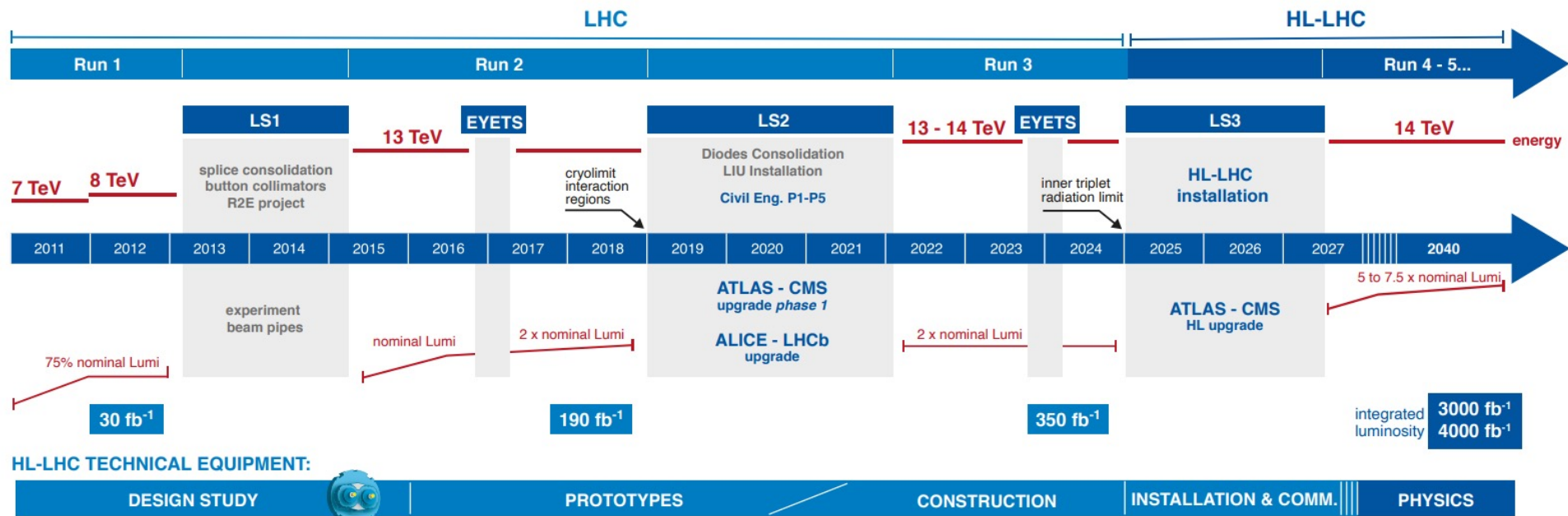
Peking University

On behalf of CMS-China

The 7th China LHC Physics Workshop (CLHCP2021)

2021.11.28

HL-LHC upgrade, challenges and CMS solution



Expected pileup (PU): ~140-200

- Improved granularity wherever possible
- in-time Pile Up mitigation: Precision Timing detectors (30ps)
- Trigger and DAQ: better selectivity, despite high PU.

Radiation damage / accumulated dose in detectors and on-board electronics=> a progressive degradation

=> Maintain performance in harsh conditions:

- Replacement of the Tracker and Endcap Calorimeter systems.
- Electronics overhaul and consolidation of the Barrel Calorimeters and Muon systems

CMS Phase-II upgrades

2019-2026, matching HL-LHC, basis for future physics !

Replacements of existing system/detector
Electronics upgrade/replacement
New detector

L1-Trigger/HLT/DAQ

- Tracks in L1-Trigger at 40 MHz
- PFlow-like selection 750 kHz output
- HLT output 7.5 kHz

Barrel Calorimeters*

- ECAL crystal granularity readout at 40 MHz
- Precision timing for e/γ at 30 GeV, for vertex localization ($H \rightarrow \gamma\gamma$)
- ECAL and HCAL new Back-End boards

Muon systems

- DT & CSC new FE/BE readout
- RPC back-end electronics
- Extended GEM coverage to $\eta \approx 3$
- New GEM/RPC $1.6 < \eta < 2.4$

MIP Timing Detector

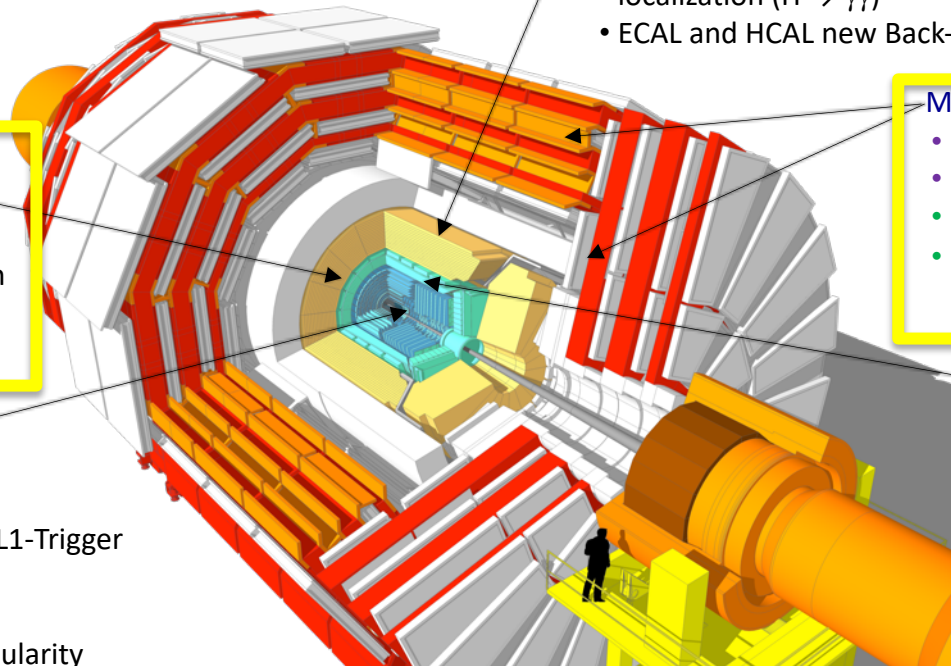
- Precision timing for PU mitigation
- Barrel layer: Crystals + SiPMs
- Endcap layer: Low Gain Avalanche Diodes

Calorimeter Endcap

- 3D showers imaging for pattern recognition
- Precision timing for PU mitigation
- Si, Scint+SiPM in Pb/W-SS

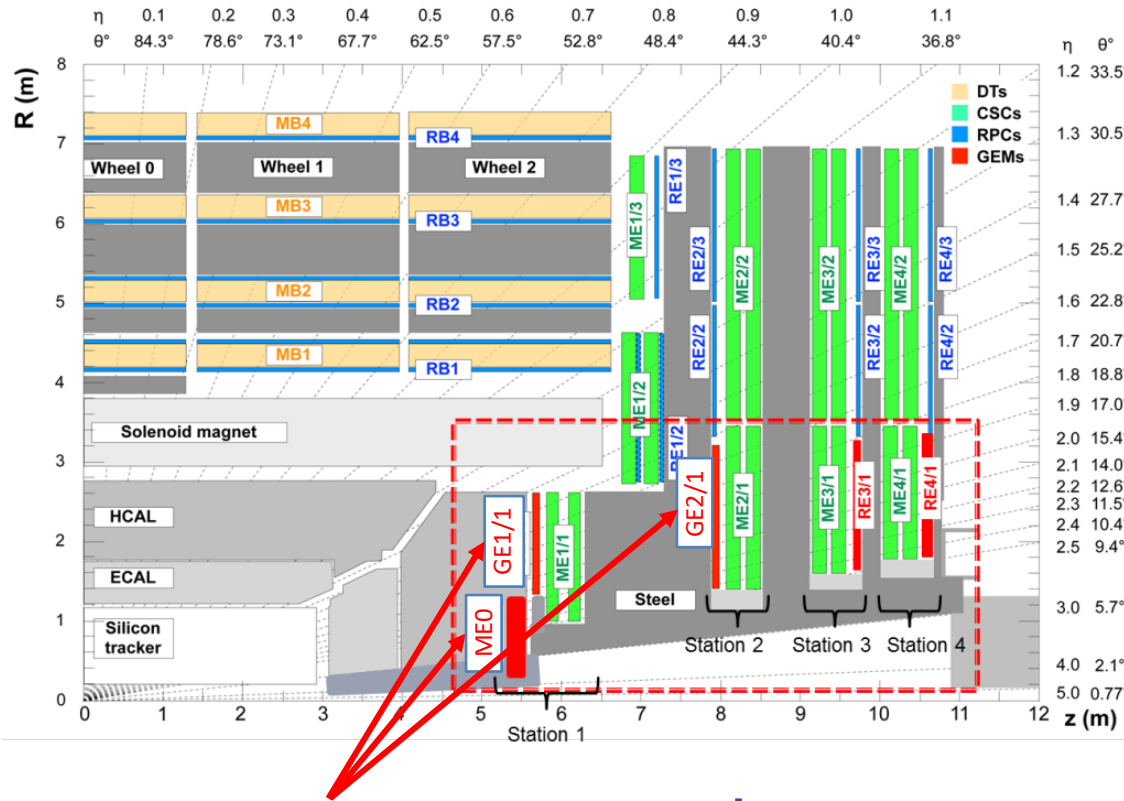
Tracker

- P_T module design for tracking in L1-Trigger
- Extended coverage to $\eta \approx 3.8$
- Much reduced material budget
- Si-Strip and Pixels increased granularity

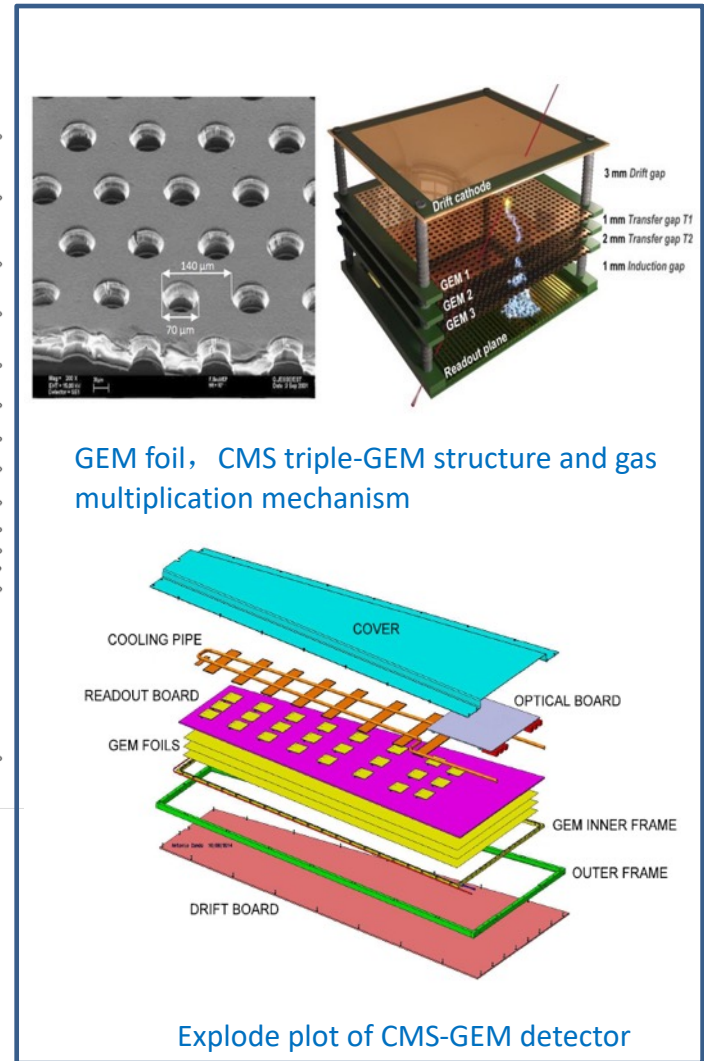


This talk focuses on: Projects with major CMS-China contributions

CMS-GEM Upgrade Project



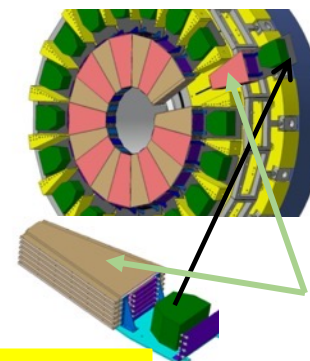
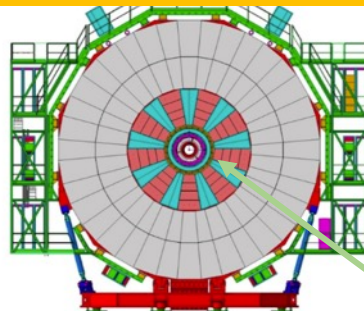
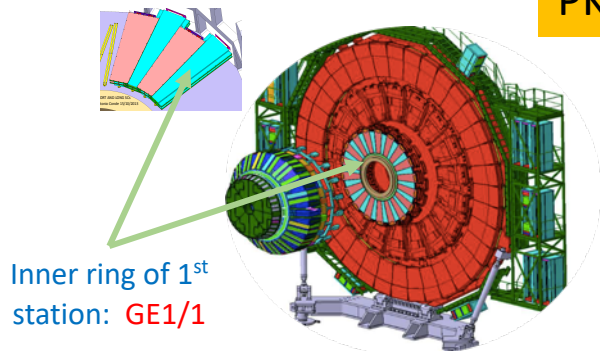
GEM (Gas Electron multipliers) Upgrade (2016-2026)



Explode plot of CMS-GEM detector

Tasks by CMS-China in GEM Upgrade

PKU+THU+SYSU+BUAA



GE2/1 demonstrator just installed

Upgrade GEM		GE1/1	GE2/1	ME0
Number of GEMs*		288 (=2×36×4)	288 (=2×18×8)	216 (=2×18×6)
Plan	R&D	2013-2017	2014-2020	2014-2022
	Mass-Production	2017-2019	2020-2022	2022-2024
	Install. & Commi.	2018-2021	2022-2024	2024-2026
Tasks of Chinese Group		Prod. & Test of all GEB in China, GEM Assembly & Test, Install. & Commission at CERN	Design & Prototyping of GEB, Assembly. & Test of ~1/8 GEM in China, Install. & Commission at CERN	Design & Prototyping of GEB, Assembly. & Test of ~1/5 GEM in China, Install. & Commission at CERN

GE1/1 see beams! Monika Mittal's talk

Annual progress

* (Total Num.=Num. of stations × Num. Of module /station × Num. of GEMs /module)

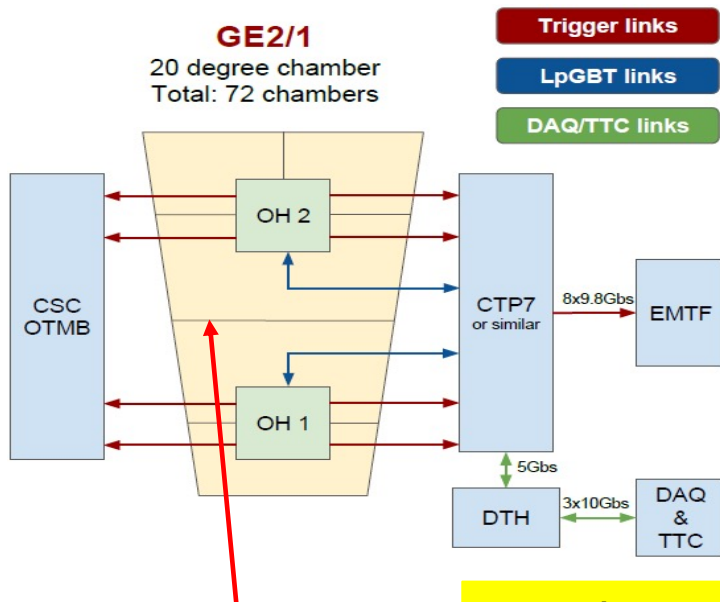
2021/11/28

CMS Phase-II Upgrade Status

Design and Prototyping of GE2/1 GEB

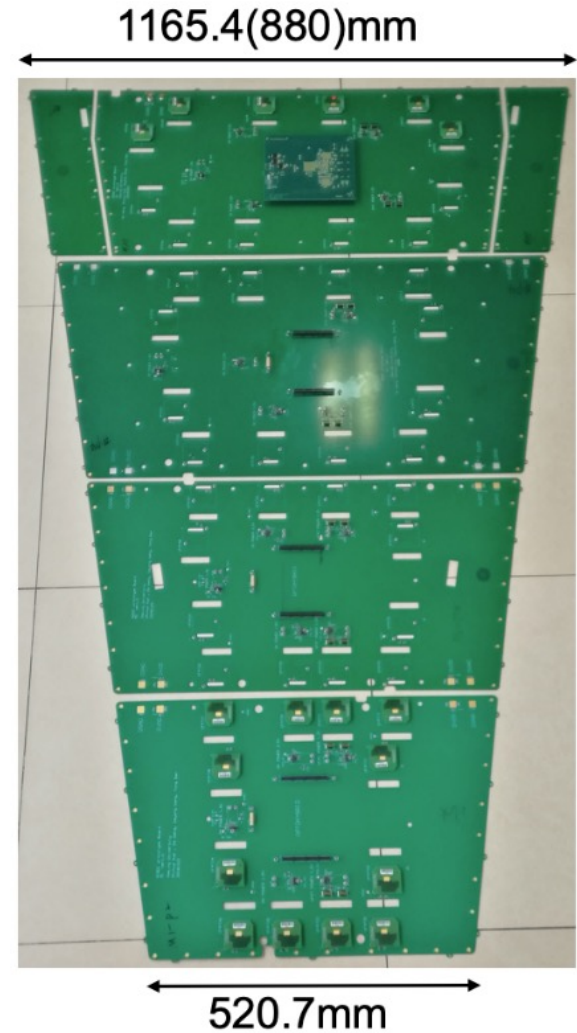
GE2/1 GEB: Design, R&D, Production and Test by Chinese Group (GE2/1 M1-M8 GEB).

During 2020-2021, three versions of 8 types **GE2/1 GEB** (~20 sets) were designed and produced in Shenzhen Sinofast Ltd. The prototypes were qualified and validated by the test in USA and CERN. Better performance than GE1/1 GEB (designed by ULB) was observed.



GE2/1 Electronics Board (GEB)

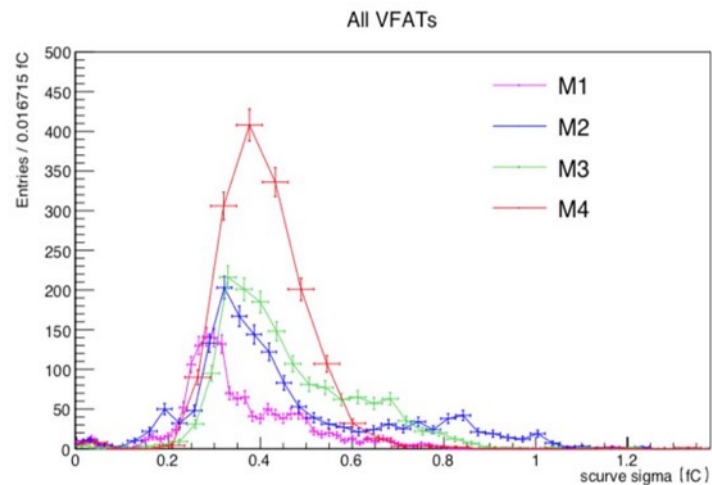
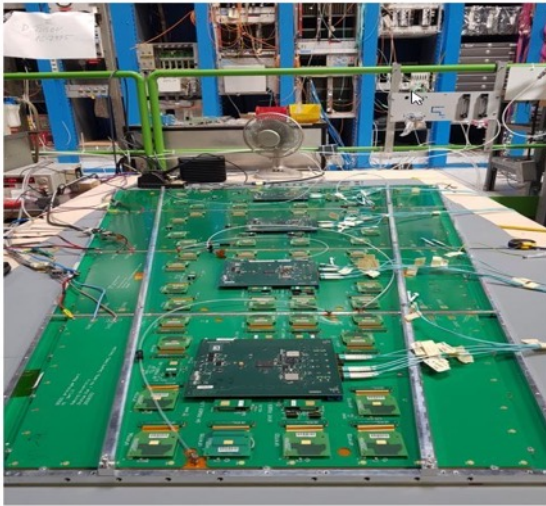
More in Zihan Liang's poster



4 types of (M1-M4) GEB 2/1 prototypes

R&D and Mass Production of GE2/1 GEB

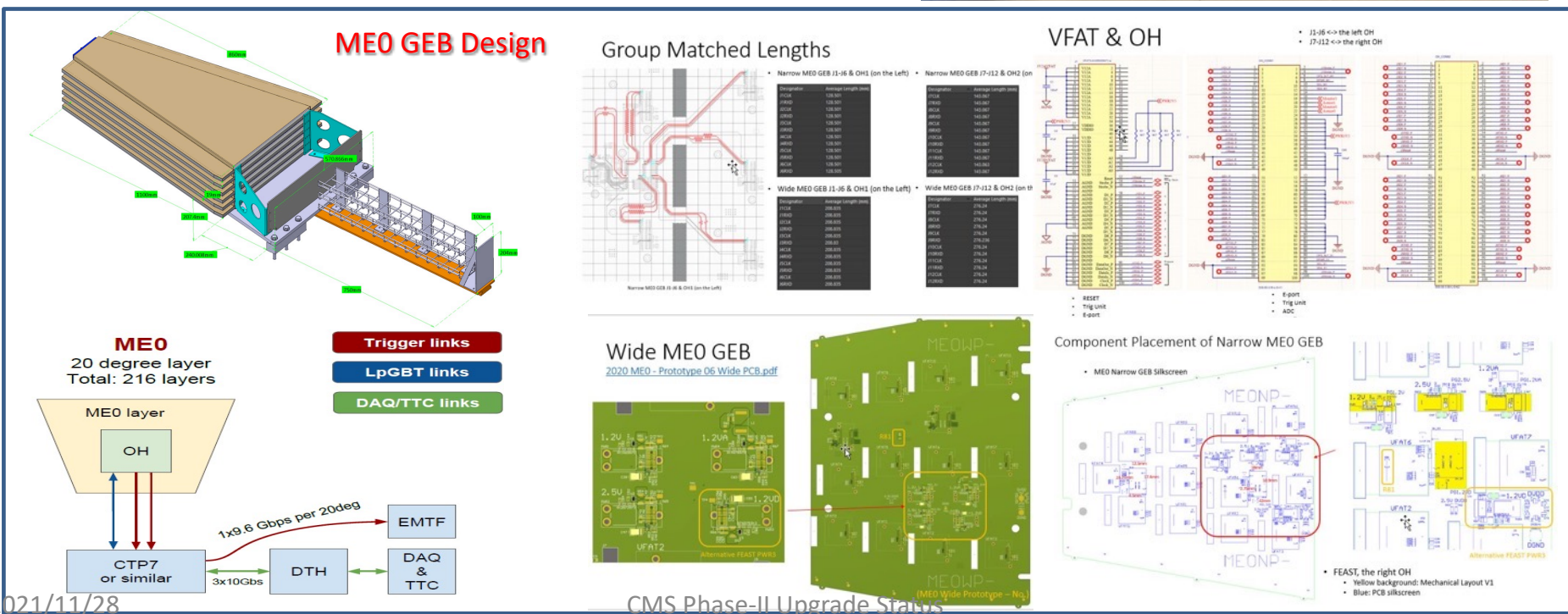
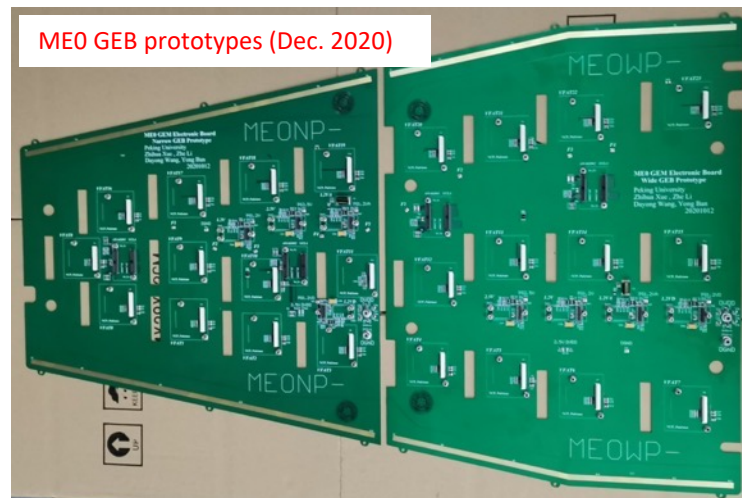
- **Jan. 20, 2021:** GEM GE2/1 **ESR Review Meeting** was hold at CERN, the presentations on GEB design, test and production plan by PKU group were reviewed and validated. Main comment: **Halogen free materials should be used on all PCB and components.**
- **Jun.-July 2021:** first batch of 6 halogen free GE2/1 M1 GEB were produced and shipped to CERN , shown satisfactory test results.
- **Oct. 2021:** mass production of GE2/1 **M1-M4** GEB (~160 sets) started, expected to be completed and shipped to CERN by early 2022, meanwhile start M5-M8 GEB production (~160 sets).



Test platform of GE2/1 M1-M4 GEB, and the result on noise test.

Design and R&D of MEO GEB

- **July 2020**: the design of the 1st version of MEO GEB by PKU group was completed; reviewed and validated by CMS-GEM collaboration;
- **Dec. 2020**: the 1st prototypes of 7 sets produced (delayed by Covid-19), shipped to CERN&USA in **Feb. 2021**, shown excellent test results.
- **later 2022**: mass production is expected to start.



External Frames and SM Structures

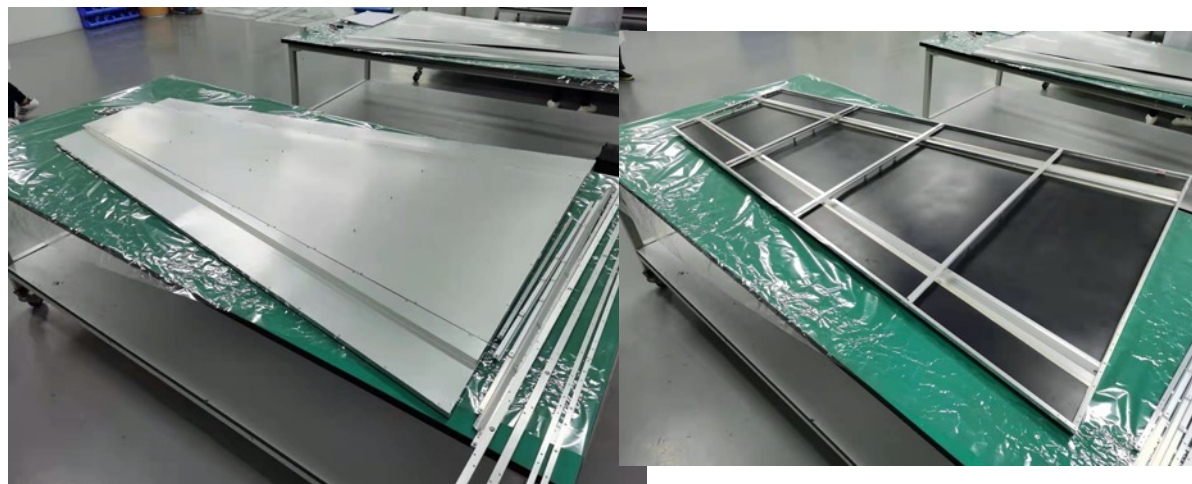
GEM External Frame: fabricated with FR4 materials with very high precision (tolerance on thickness < 0.03 mm)

- Start test production in 2019 in China, approved by CMS-GEM review committee in **Jun. 2020**;
- **May 2021:** production of all GE2/1 FR4 external frames (320 sets) completed, tested and shipped to CERN

- **Screen and supporting structure of GE2/1 Super-Module:** 2 types ($\sim 1 \times 2 \text{ m}^2$) holds 8 GEM chambers (M1-M8), providing mechanical support, insulation, screening
- **Apr. 2021:** start facility update and test production. Two sets of prototypes produced in Oct. and passed QC.
- **~early 2022:** start mass production (~ 40 sets)



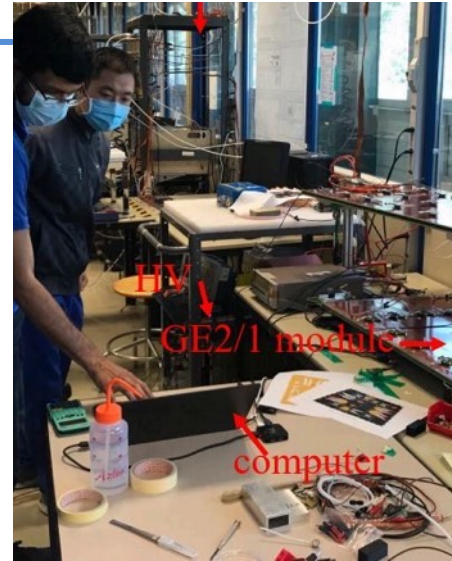
GEM FR4 ext. frames produced



Prototypes of screen and supporting structure of GE2/1 Super-Module

PKU Production Site and activities at CERN

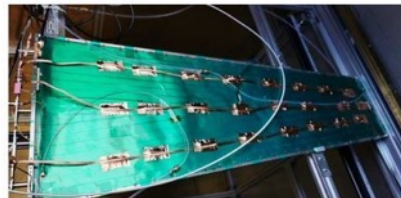
- PKU GEM assembly and QC laboratory **ready**, with cleanroom and hardware/software platforms
- **Mar. 2021**: PKU GEM Lab. passed the review of CMS-GEM collaboration, becomes one of the **official CMS-GEM production sites**.
- **Jun.-Sept. 2021**: PKU members participated the assembly and test of GE2/1 M1 GEM at CERN,
- **~mid 2022**: start production of GE2/1 M5 GEM (~40 chambers) in PKU.



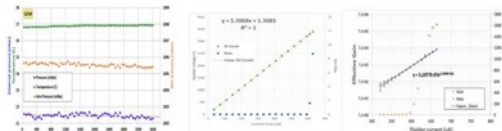
- Completed gas-tightness, HV performance and gain test etc. with **full-size GE1/1 GEM**, QC procedure setup done.



GEM X ray gain test at PKU



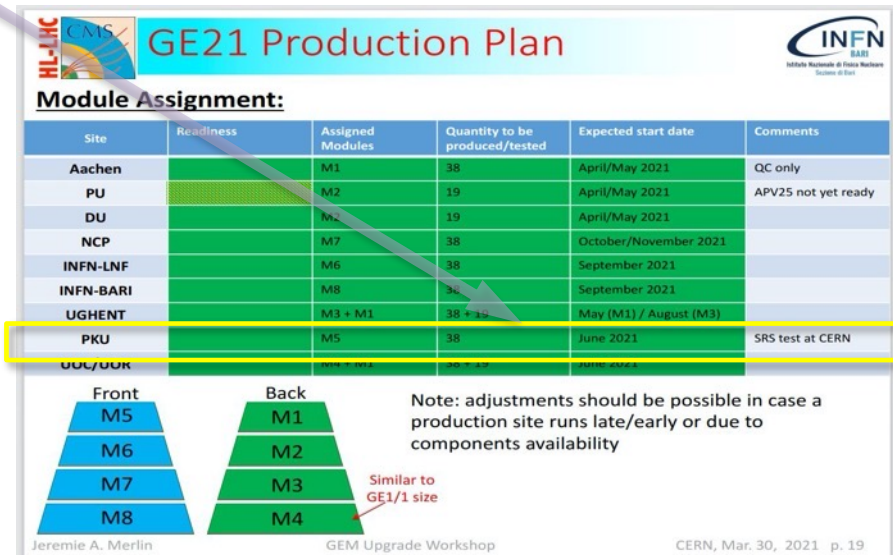
Full-size GE1/1 GEM detector



Test results of GEM gas-tightness, HV performance and gain

→ **GEM Production site in PKU is ready**

Test of Full-size GE1/1 GEM at PKU lab.

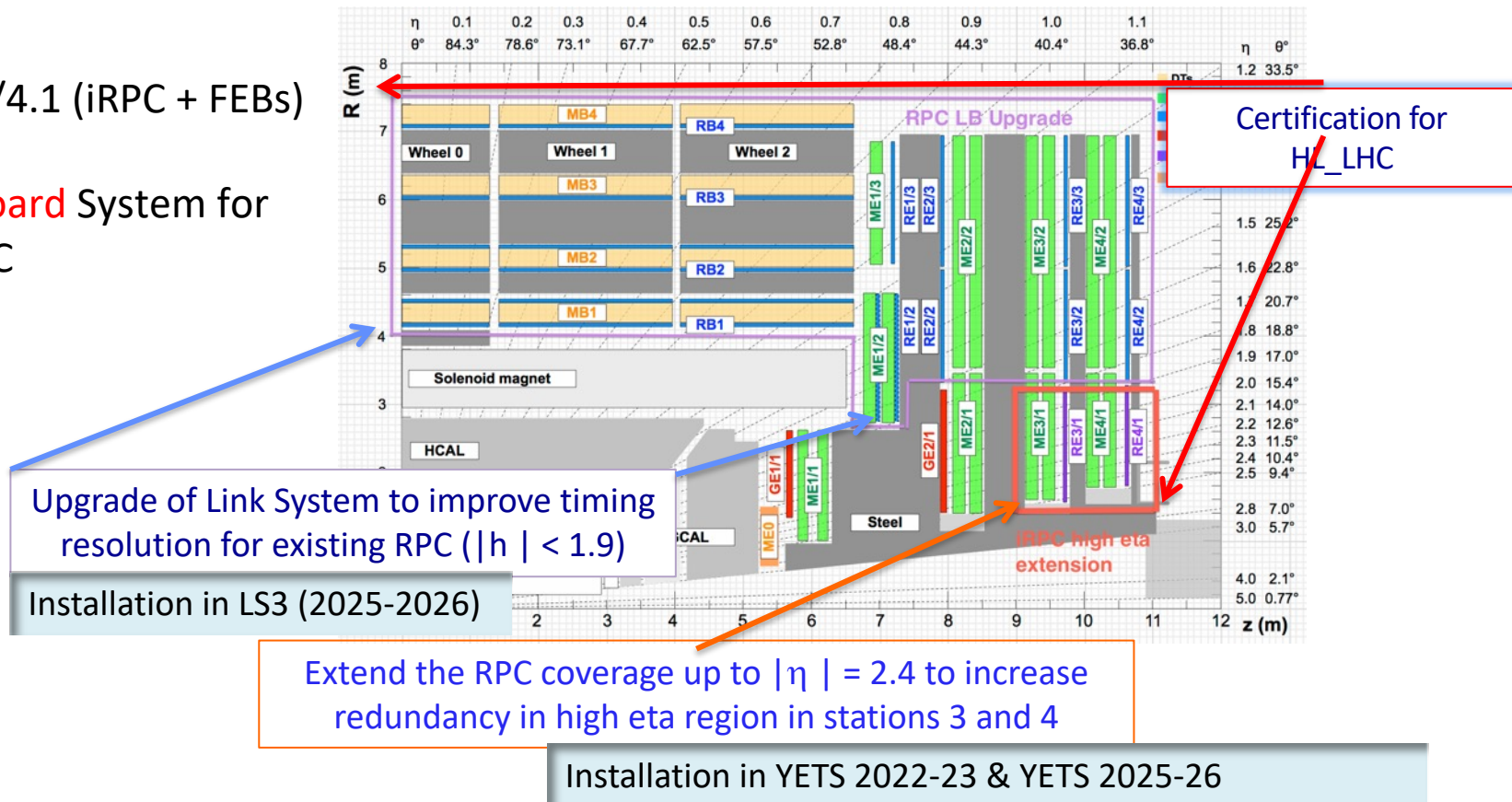


More details in Aera Jung's talk

RPC Upgrade Project

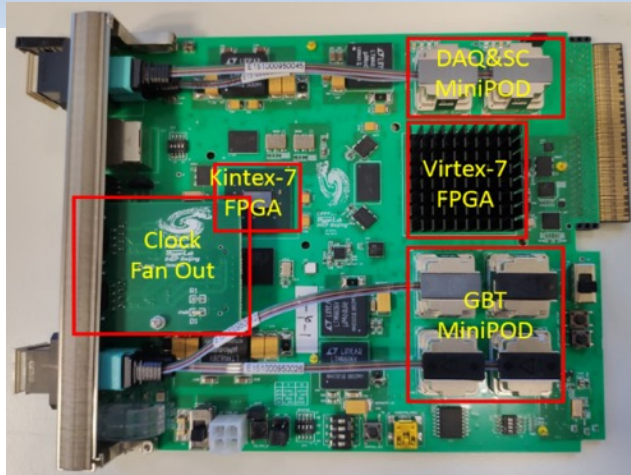
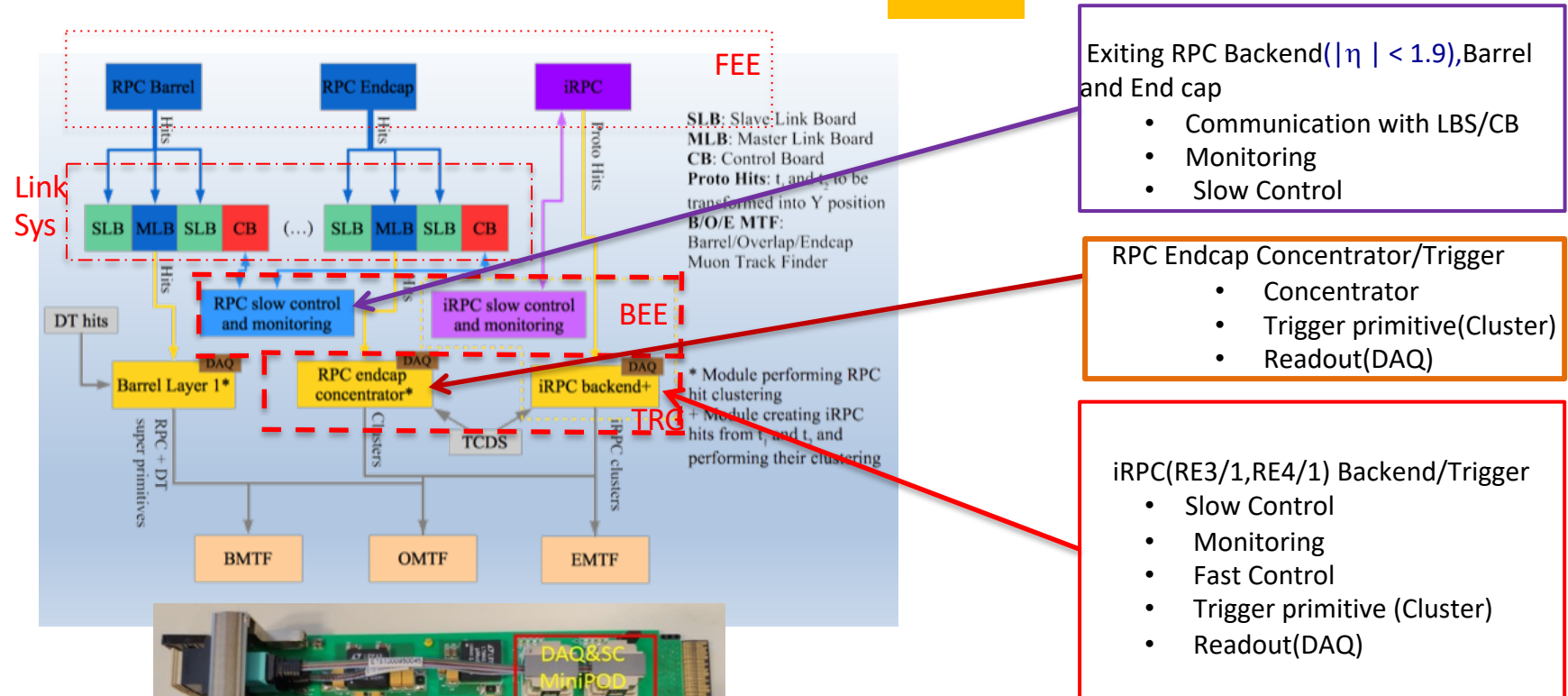
New RE3.1/4.1 (iRPC + FEBs)

New LinkBoard System for present RPC



RPC/iRPC TRIG/Backend Electronics

IHEP



Demonstrator 2021/2022 and Interim 2023/2024 Installation

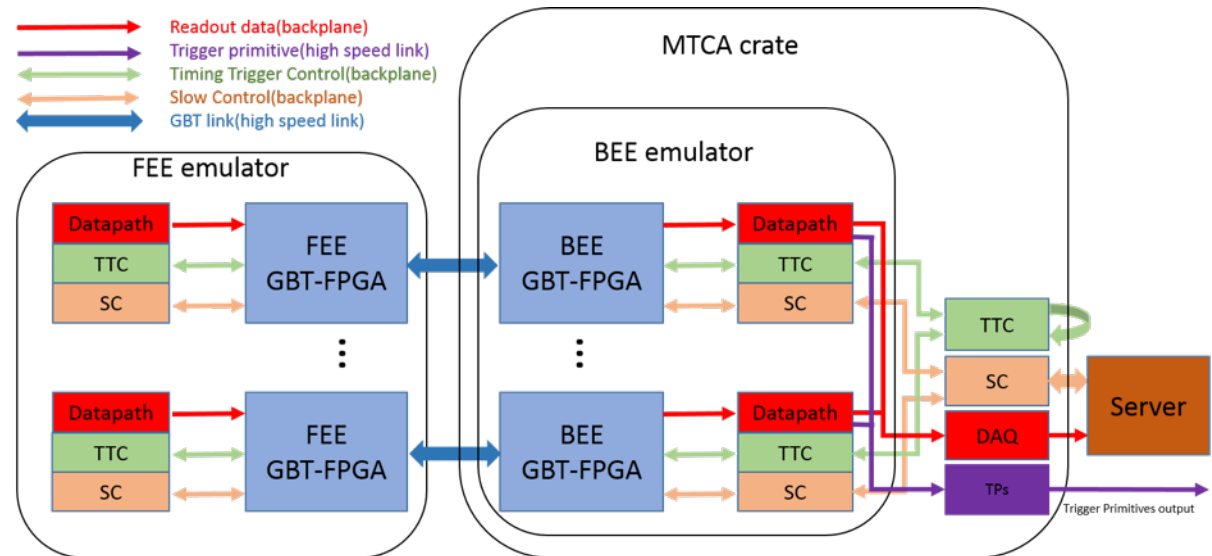
Backend electronic and trigger board by IHEP is key hardware component for backend and trigger

Backend demonstrator: fw and sw

Before joint test with iRPC/FEB, Emulator system were developed and tested to check full functionalities of BE/Trigger.

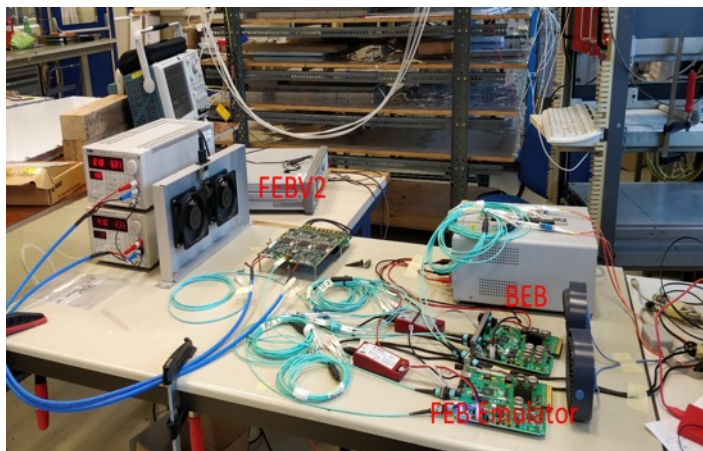
See SONG Jianing's talk

- Fast control/TTC
- Slow Control/SC
- Readout/DAQ
 - Data driven readout
- Trigger Primitives
- FE also emulated
 - Check-Sort-Push Mechanism

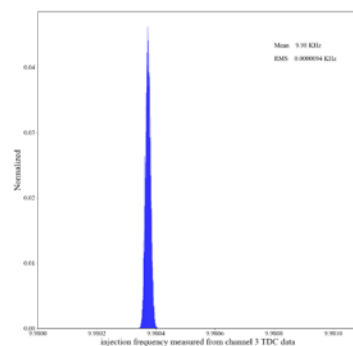
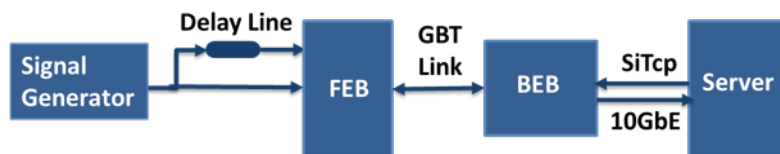


Test working in April/May

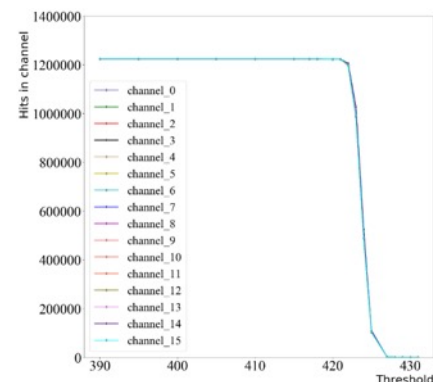
iRPC FEE-BE/Trigger Joint test



- FEE Emulator ,FEB and BE Joint test system was set up in 904 since July 2021.
- Preliminary results shows that BE/Trigger can configure and readout data correctly from iRPC FEB.



Test signal frequency measurement



Petiroc threshold scan after calibration



Fan-out output signal



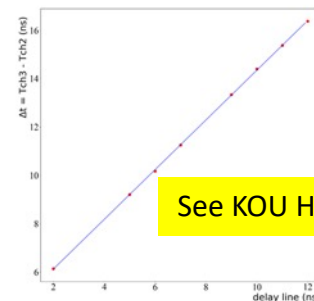
Oscilloscope confirms the delay value



FEB Injection signal

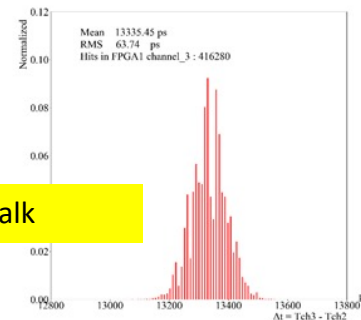


FEB Injection board



See KOU Hanjun's talk

Time measurement by adjusting delay line

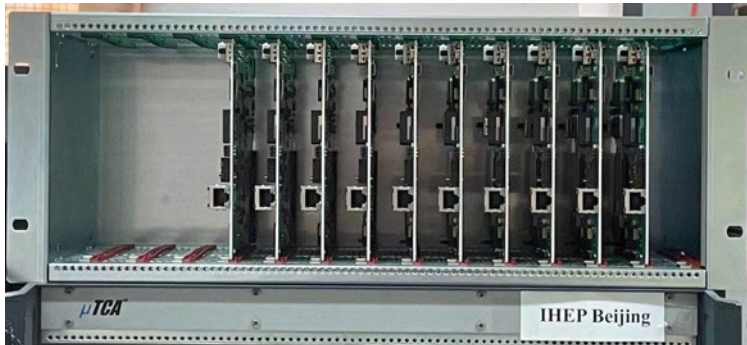


Time resolution of FEB TDC

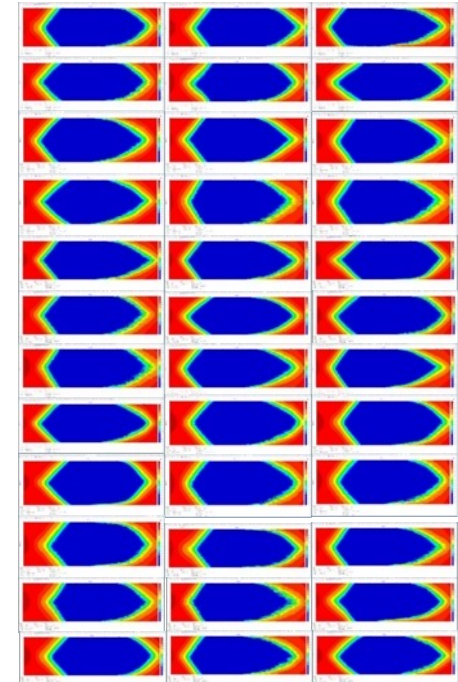
MTCA Mini-Production for installation

See ZHAO Jingzhou's talk

- Finished Mini-Production for 2022/23 Installation done .
- MicroTCA Qualification OK.
- Ready for transportation to CERN .



Serial VO Links										Serial VO Scans					
	us	BER	Loopback	Mode	Status	Errors	Bits								
10Gbps							1.165E-15								
Link 0	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 1	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 2	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 3	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 4	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 5	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 6	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 7	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 8	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 9	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 10	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 11	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 12	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
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Link 14	9.998 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
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Link 17	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
Link 18	10.000 Gbps	1.165E-15	None	✓	Locked	Latched	0E0	0.584E14							
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Ungrouped Links															



HGCal Design and Parameters

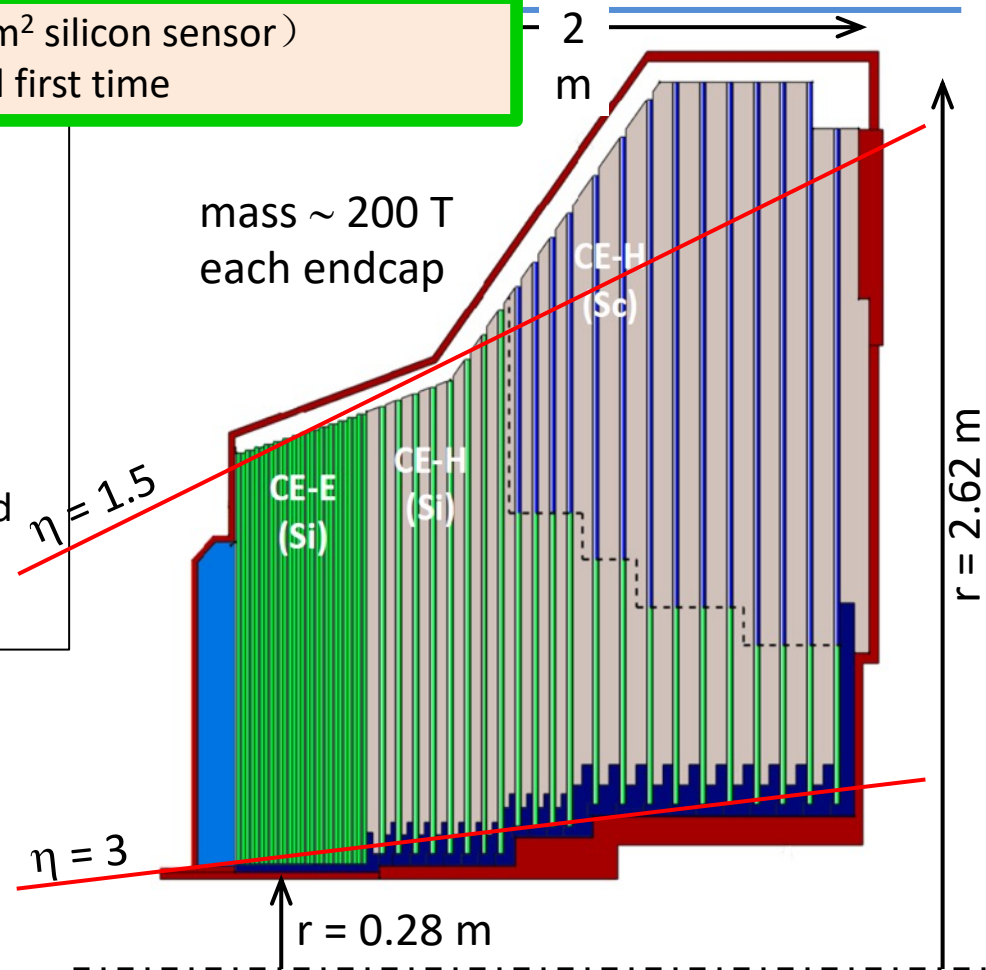
~31k Si Module (640m² silicon sensor)
a 5D calorimeter build first time

Key Parameters :

- HGCal covers $1.5 < \eta < 3.0$
- Full system maintained at -30°C
- ~640 m² of silicon sensors
- ~370 m² of scintillators
- 6.1M Si channels, 0.5 or 1.1 cm² cell size (6M)
- 240k scint-tile channels ($\eta-\phi$)
- Data readout from all layers
- Trigger readout from alternate layers in CE-E and all in CE-H
- ~31k Si modules (incl. spares)

challenges:

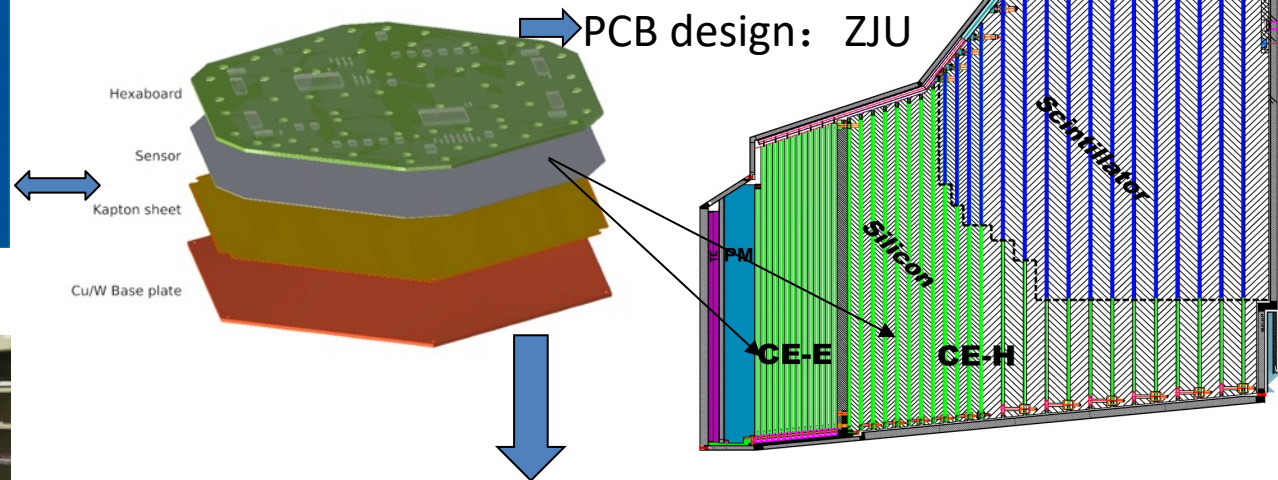
2MGy does
140 pileup
220kW heat load
640m² silicon sensor
...



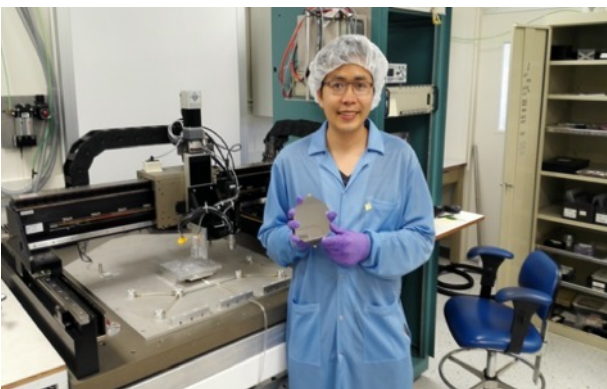
Electromagnetic calorimeter (CE-E): Si, Cu/CuW/Pb absorbers, 28 layers, $25.5 X_0$ & $\sim 1.7\lambda$
Hadronic calorimeter (CE-H): Si & scintillator, steel absorbers, 22 layers, $\sim 9.5\lambda$ (including CE-E)

Major task for China HGCal: MAC

IHEP+ZJU+THU+FDU



Module Assembly Centers (MAC):
IHEP, NTU, Indian, UCSB, TTU, CMU
~5200 modules per MAC

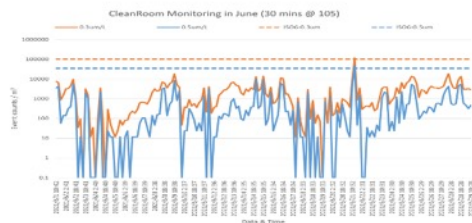
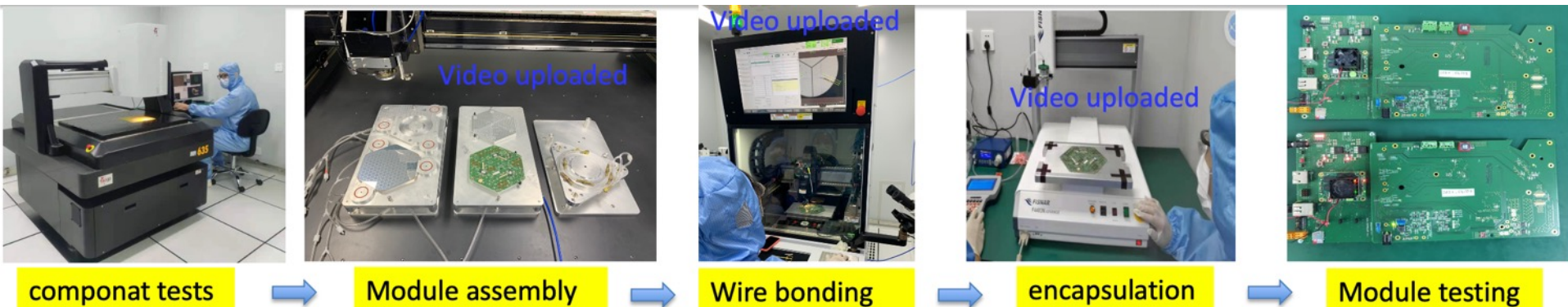


Since first silicon module(6 inch) in 2016, IHEP has close collaboration with UCSB and participate ~20 module assembly



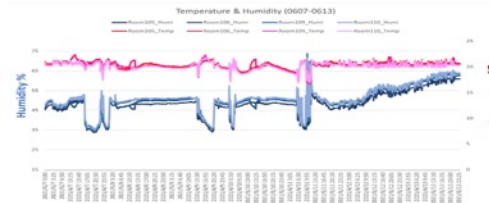
Cost: 69 M CHF
IHEP MAC will produce >
100 m² silicon module

Production chain at IHEP MAC set up and qualified



Cleanroom status

- Cleanness
- Temperature
- Humidity



- Clean room and major equipment are installed, operator trained
- Fixture for gantry, wire bonder, pull tester, encapsulation are fabricated
- Glue pattern for assembly, encapsulation and wire bonding code are tested
- Go through full production chain for the first time on real componats (next slide)

- Silicon module assembly centres: MACs qualified (UCSB, IHEP, and NTU), are close (CMU and TTU), and TIFR now has a green light to order a g
- SiPM market survey closed. Moulded tile prototyping well advanced. Machined cast tile prototypes made and under test, and tileboards development and test advancing well
- SiPM-on-Tile light yield results consolidated from different tests. Inputs collected for the optimization of the overall layout, and calibration procedure being studied for end-of-life with lower S/N
- Tilemodule assembly: automated tile wrapping and tilemodule assembly equipment is working in the TACs
- HGCR0Cv3 is under test and the analogue results very encouraging, some issues with new digital elements to be understood, and packaging has suffered delays
- ECON-T-P1 submitted. ECON-D design well advanced realistic. ECON-T-P2 planned. ECON design and verification in progress, depth of the team

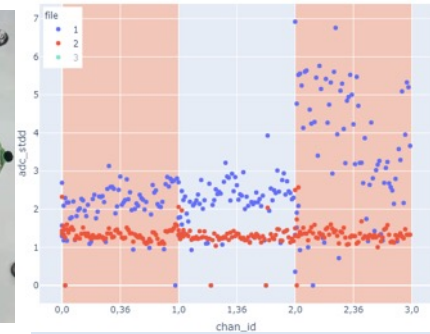
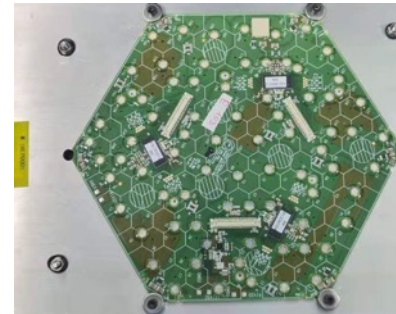
Details in Yong Liu's talk



HGC project manager's site qualification report to P2UG

Production of 2 functional 8 inch module

- Successfully build 2 8 inch HGCal silicon module
 - HGC first functional 8" silicon module
 - Latest HGCROC ASICs
 - Low noise ($\sim 2-3$ ADC)
 - [IHEP news report](#)
- Both modules tested by test beam
 - 2021-9 test first module at CERN beam: IHEP module001
 - 2021-10 test second module at CERN beam: IHEP module 002

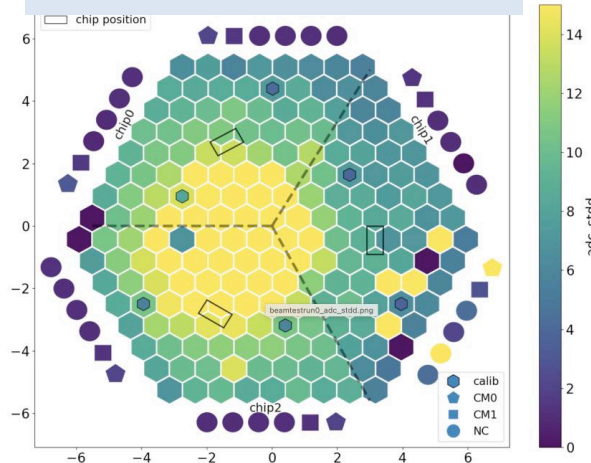


Noise **with/w.o.**
sensor

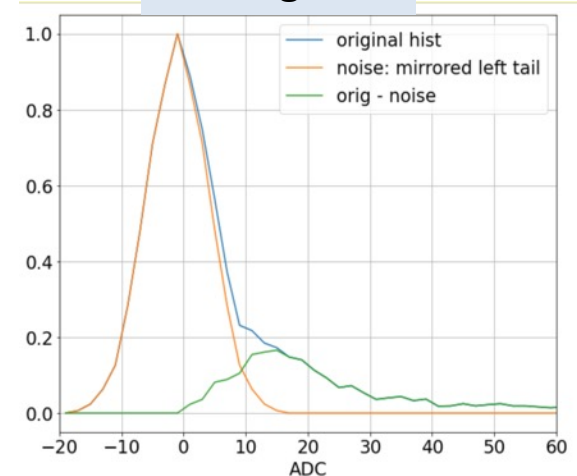
First time see beam in
8" silicon module



Beam shower event



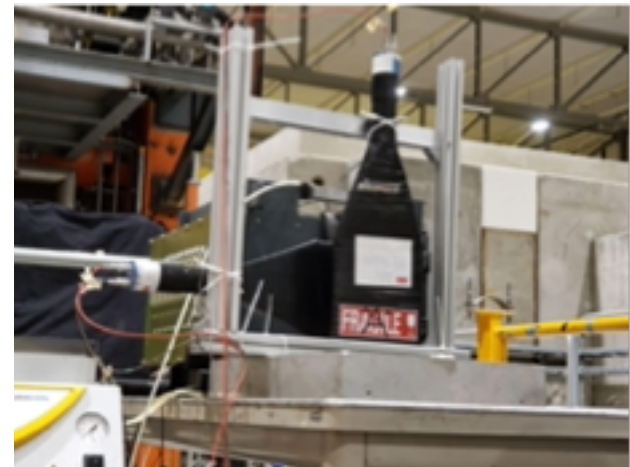
MIP signal



Details in Feng Wang's talk

FE ASIC/module/beam test at CERN

- ~130 HGCROC2 chips tested in April
- ~20 hexaboards received and tested in end of June
 - IHEP produce modules use these hexaboards
- Prepare 2021 Sept. Oct. Beam test, take shifts, and data analysis
- Develop hexaboard tests framework for MACs

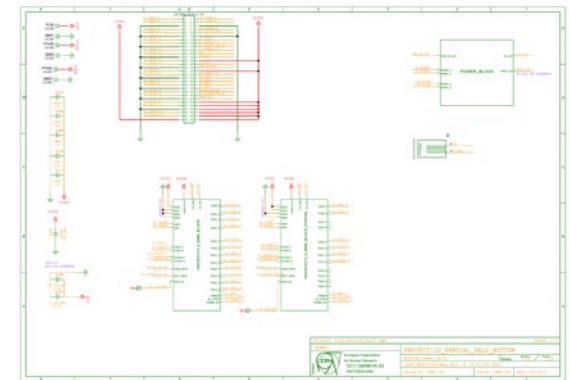
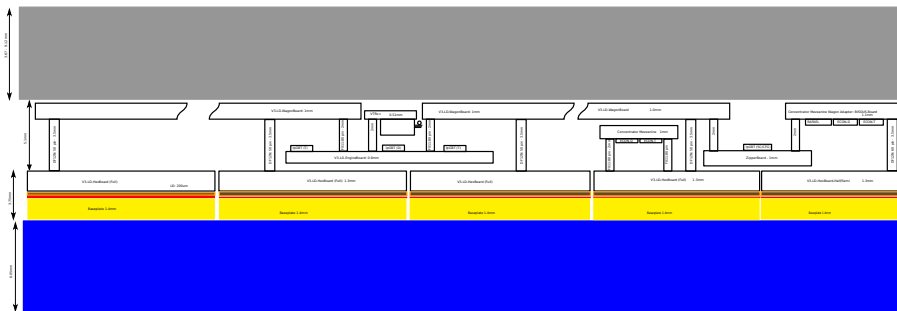
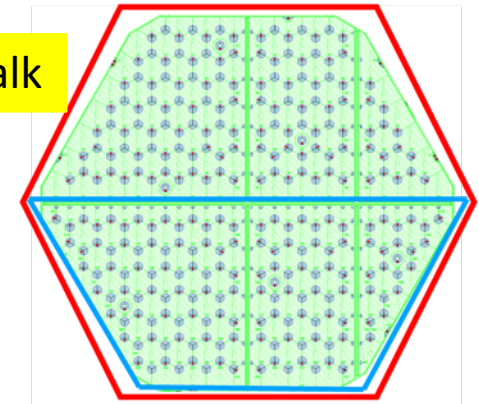
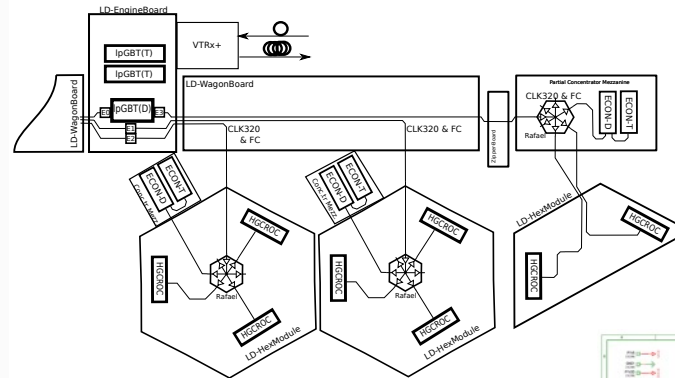


IHEP contributions

A. Kapoor
E. Chapon
F. Monti

ZJU

- Full module**
Half module



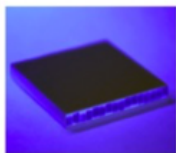
CMS timing detector MTD

CMS-China officially joined MTD in 2021

- [PKU](#), [BUAA](#) and [THU](#) joined MTD barrel (BTL) studies which uses LYSO+SiPM
- [USTC](#) plans to join the MTD endcap (ETL) studies which uses LGAD
- Actively communicated with MTD collaboration, built local labs, set up testing bench, and already made contributions to SiPM testing

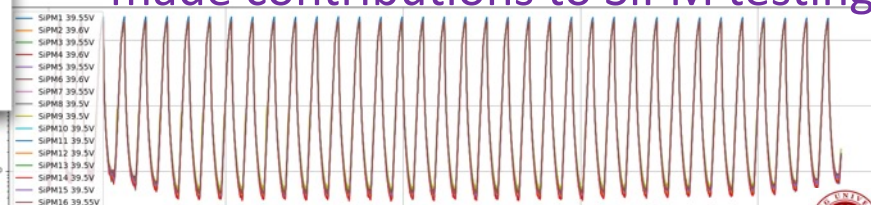
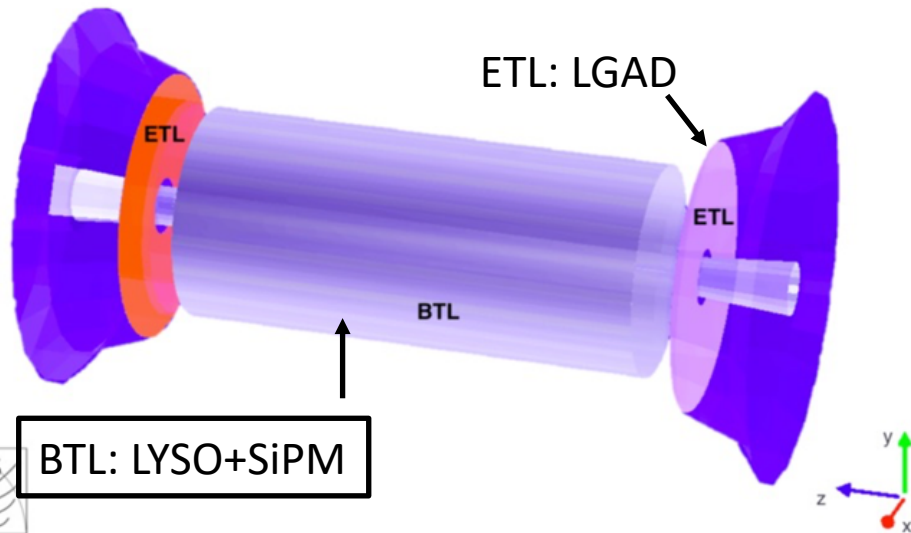
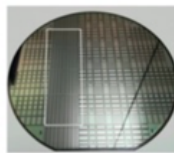
BTL: LYSO bars + SiPM readout:

- TK / ECAL interface: $|n| < 1.45$
- Inner radius: 1148 mm (40 mm thick)
- Length: ± 2.6 m along z
- Surface ~ 38 m²; 332k channels
- Fluence at 4 ab⁻¹: 2×10^{14} n_{eq}/cm²

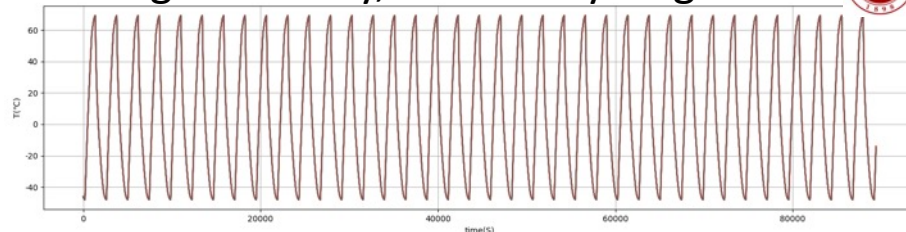


ETL: Si with internal gain (LGAD):

- On the CE nose: $1.6 < |n| < 3.0$
- Radius: $315 < R < 1200$ mm
- Position in z: ± 3.0 m (45 mm thick)
- Surface ~ 14 m²; ~ 8.5 M channels
- Fluence at 4 ab⁻¹: up to 2×10^{15} n_{eq}/cm²



Peking University, thermal cycling



More details in Xiaohu Sun's talk



Summary

- CMS Phase-II upgrade projects are fully launched and progress well, with many important contributions from CMS-China
- GEM:
 - GE1/1 fully installed, commissioned and see the first beam;
 - GE2/1 GEB designed and validated by CMS-China and 1/8 chamber production and QC in China to start soon;
 - MEO under prototyping, with both electronics and chamber
- iRPC electronics and trigger
 - Backend/Trigger development done and verified with emulator system;
 - First step of joint test with iRPC/FEBV2 is successful;
 - Data readout tested with FEE injection system and further test ongoing
- HGCALE
 - Passed IHEP MAC site qualified, silicon module production developed;
 - CMS first 2 8 inch silicon module built at IHEP, validated by CERN test beam;
 - Half-exaboard PCB Designed by ZJU team
- MTD: new contributions from CMS-China, local lab set up